

Summary Report on ITherm 2008

Yogendra Joshi, Program Chair

The ITherm 2008 conference was held at the Hilton at Walt Disney World Resort in Orlando, Florida during May 28-31, 2008. The Conference General Chair was Dr. Tom Lee from TSMC, Inc. and Program Chair was Prof. Yogendra Joshi from Georgia Institute of Technology. The conference was attended by approximately 260 registered attendees and included nearly 170 technical paper presentations.

The conference began on May 28 with a total of thirteen advanced short courses (4 hours each) and tutorials (2 hours each) presented by expert instructors in morning and afternoon sessions. In general, the short courses covered established topics of general interest, whereas the tutorials covered emerging themes. During May 29-May 31, the technical papers were presented in 38 sessions covering four Tracks: Thermal Management, Mechanics and Materials, Emerging Technologies, and Energy Efficient Electronics. The last of these, is a newly established topic of significant current interest. All papers in this Track were presented in the form of posters in a single dedicated session on May 30. In all, 18 technical sessions were held in Thermal Management, 8 in Mechanics and Materials, 6 in Emerging Technologies, and 6 in Energy Efficient Electronics.

In addition to the technical papers, there were three Keynote/Invited presentations. The opening Keynote titled, "Emerging Systems Packaging Technologies", was delivered on the morning of May 29 by Prof. R.R. Tummala from Georgia Institute of Technology. The ITherm Achievement Award Luncheon talk titled, "IBM, Mainframes, and Environmentals", was delivered by Dr. R.R. Schmidt from IBM. There were four panel sessions during the conference. These included: "Thermal Management Challenges for Military Electronics", "Cooling Challenges and Energy Efficiency in Low Form Factor Electronics", "Cyber Infrastructure Resources for Thermal Management", and "Energy Efficient Data Centers".

A key feature of the ITherm conference has historically been the link with the Electronics Components and Technology Conference (ECTC) through the joint Exhibits program. This year the distance between the two venues required the use of shuttle buses. Visits to the Exhibit were arranged for the evening reception on May 28, and during the afternoon of May 29. For ITherm 2010, the proximity of the two conference venues will make this linkage even stronger.

The Awards Luncheon was the final event of the conference, held on May 31. At this event, Best Paper Awards to the authors of the highest rated paper from each of the four Tracks were presented. In addition, two papers from the Thermal Track and one from the Mechanics Track received the Outstanding Paper Awards.